

MPS RC Vacuum

High Precision Grinding Machine for grinding of non-ferrous material and semiconductor material

Grinding-

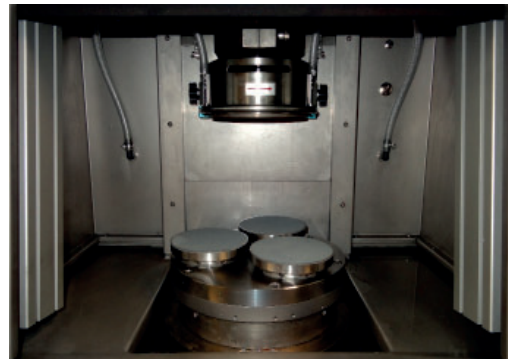
machines

Genauigkeits
Maschinenbau
Nürnberg GmbH



Technical Data

Motor	2,2 kW
Spindle r.p.m	2850 min ⁻¹
Power connection	4 kW
Rotary table	
Diameter	ø300 mm
R.p.m	0 - 30 min ⁻¹
Axial run-out	< 2 µm
Grinding height above rotary table	
Diamond / CBN	300 mm
Grinding wheel	
Diamond / CBN	ø175 mm
Number of chucks	
2" 3" 4" 5" 6"	18 8 5 3 2
Fine infeed	
Range	300 mm
Min. step	1 µm
Weight	350 kg
Required space	850x700 mm



Application

Batch production, research and development departments, where materials such as silicon, gallium arsenide, germanium, indium phosphid, aluminum oxide, piezo ceramic, quartz, ferrite, etc. have to be ground with micron precision.

Characteristics

Surface grinding machine with vertical spindle, cup grinding wheel, frequency-controlled rotary table, motor grinding spindle and automatic high-precision fine infeed.

Features

- Motor spindle
- Rotary table
- Automatic fine infeed
- Programmable grinding cycles
- Coolant supply
- Vacuum chucks (porous ceramic)
- Wafer diameter 2" to 6"

Accessories (optional)

- Wet grinding system
- Vacuum system
- Vacuum chucks
- Diamond grinding wheel